

XN04130 (XN4130)

Silicon PNP epitaxial planer transistor

For amplification of low frequency output

Features

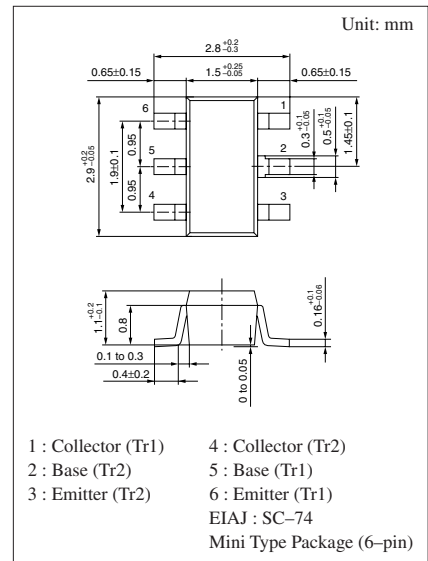
- Two elements incorporated into one package.
(Transistors with built-in resistor)
- Reduction of the mounting area and assembly cost by one half.

Basic Part Number of Element

- UNR1130(UN1130) × 2 elements

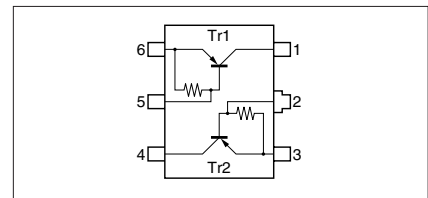
Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Ratings	Unit	
Rating of element	Collector to base voltage	V_{CBO}	-15	V
	Collector to emitter voltage	V_{CEO}	-15	V
	Emitter to base voltage	V_{EBO}	-7	V
	Collector current	I_C	-0.5	A
	Peak collector current	I_{CP}	-1	A
Overall	Total power dissipation	P_T	300	mW
	Junction temperature	T_j	150	°C
	Storage temperature	T_{stg}	-55 to +150	°C



Marking Symbol: OF

Internal Connection



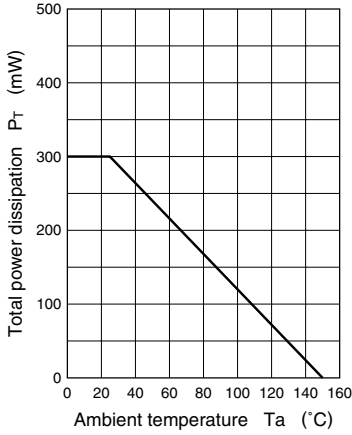
Electrical Characteristics (Ta=25°C)

Parameter	Symbol	Conditions	min	typ	max	Unit
Collector to base voltage	V_{CBO}	$I_C = -10\mu A, I_E = 0$	-15			V
Collector to emitter voltage	V_{CEO}	$I_C = -1mA, I_B = 0$	-15			V
Emitter to base voltage	V_{EBO}	$I_E = -1mA, I_C = 0$	-7			V
Collector cutoff current	I_{CBO}	$V_{CB} = -10V, I_E = 0$			-0.1	μA
Forward current transfer ratio	h_{FE1}	$V_{CE} = -2V, I_C = -500mA^*$	80		280	
	h_{FE2}	$V_{CE} = -2V, I_C = -1A^*$	50			
Collector to emitter saturation voltage	$V_{CE(sat)}$	$I_C = -300mA, I_B = -6mA$		-0.2	-0.3	V
Base to emitter saturation voltage	$V_{BE(sat)}$	$I_C = -300mA, I_B = -6mA$		-0.9	-1.3	V
Transition frequency	f_T	$V_{CB} = -10V, I_E = 50mA, f = 200MHz$		130		MHz
Collector output capacitance	C_{ob}	$V_{CB} = -10V, I_E = 0, f = 1MHz$		22		pF
Base to emitter resistance	R_{BE}		-30%	10	+30%	k Ω

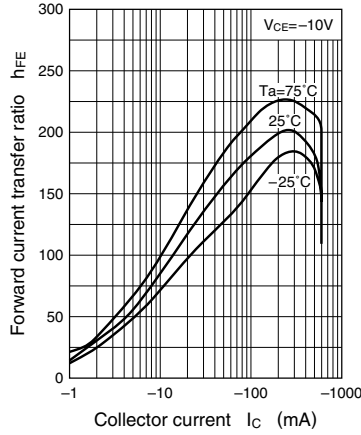
*Pulse measurement

Note.) The Part number in the Parenthesis shows conventional part number.

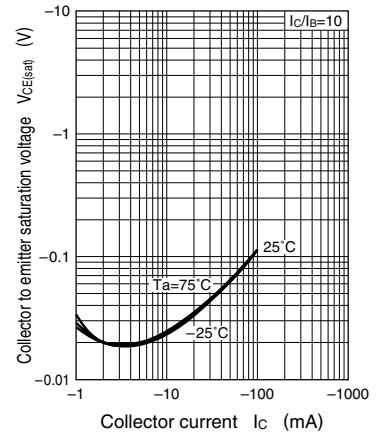
$P_T - T_a$



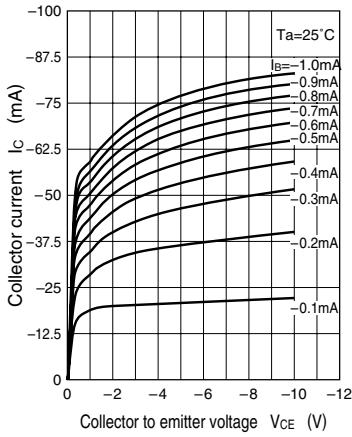
$h_{FE} - I_C$



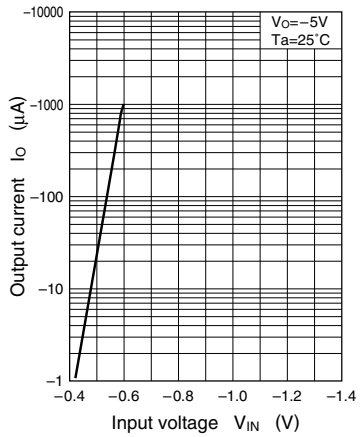
$V_{CE(sat)} - I_C$



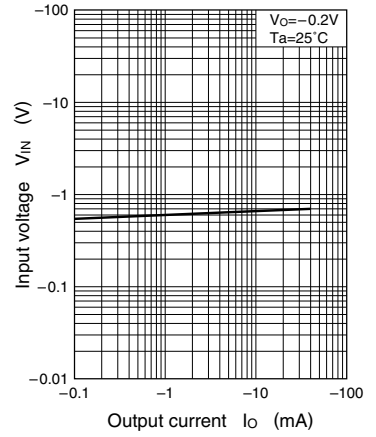
$I_C - V_{CE}$



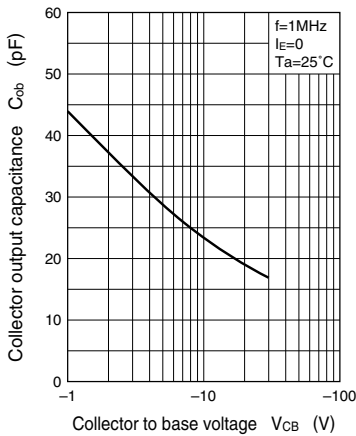
$I_O - V_{IN}$



$V_{IN} - I_O$



$C_{ob} - V_{CB}$



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